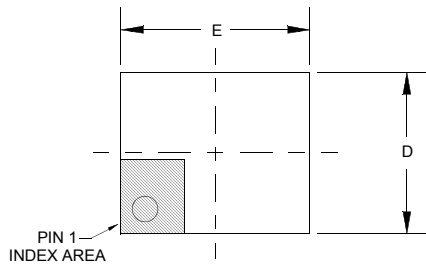
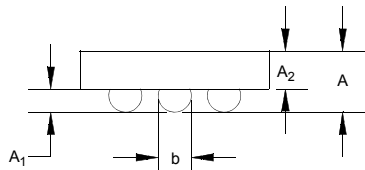


Plastic Packages for Integrated Circuits

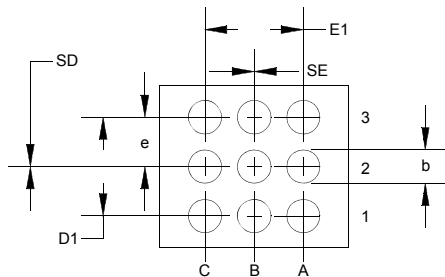
Wafer Level Chip Scale Package (WLCSP 0.4mm Ball Pitch)



TOP VIEW



SIDE VIEW



BOTTOM VIEW

W3x3.9C

3x3 ARRAY 9 BALL WAFER LEVEL CHIP SCALE PACKAGE

SYMBOL	MILLIMETERS
A	0.445 Min, 0.495 Nom, 0.545 Max
A ₁	0.190 ±0.025
A ₂	0.305 ±0.025
b	0.270 ±0.030
D	1.315 ±0.020
D ₁	0.800 BASIC
E	1.535 ±0.020
E ₁	0.800 BASIC
e	0.400 BASIC
SD	0 BASIC
SE	0 BASIC
Number of Bumps: 9	

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NOTES:

1. Dimensions are in Millimeters.